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REVISIONS

P	LTR	DESCRIPTION	DATE	DWN	APVD
	D	ECR-16-014363	11OCT2016	FL	SY

NOTE:

1. MATERIAL:

HOUSING (SEE TABLE): PA46 OR PA9T, UL94 V-0, COLOR: BLACK.

CONTACTS: PHOSPHOR BRONZE.

BOARDLOCK: BRASS.

2. FINISH:

2.1 CONTACTS: (SEE TABLE) GOLD PLATED ON CONTACT AREA,
2.54um [100u"] MIN. MATTE-TIN ON SOLDER TAIL,
WITH ENTIRE CONTACT UNDERPLATED 1.27um [50u"] MIN. NICKEL.2.2 BOARDLOCK: 2.54um [100u"] MATTE-TIN PLATING ALL OVER
NICKEL 1.27um[50u"] MIN. UNDERPLATED OVERALL.

3. WAVE SOLDER CAPABLE TO 265°C MAX. PER TE SPEC. 109-202, CONDITION B.

4. WEIGHT:

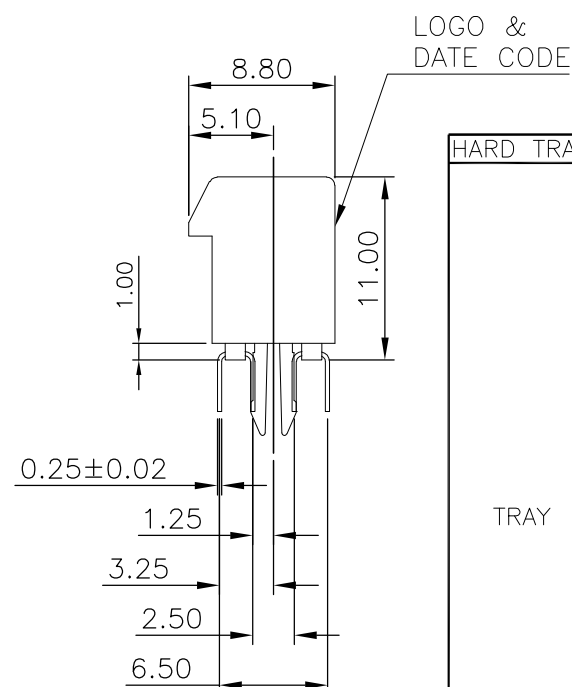
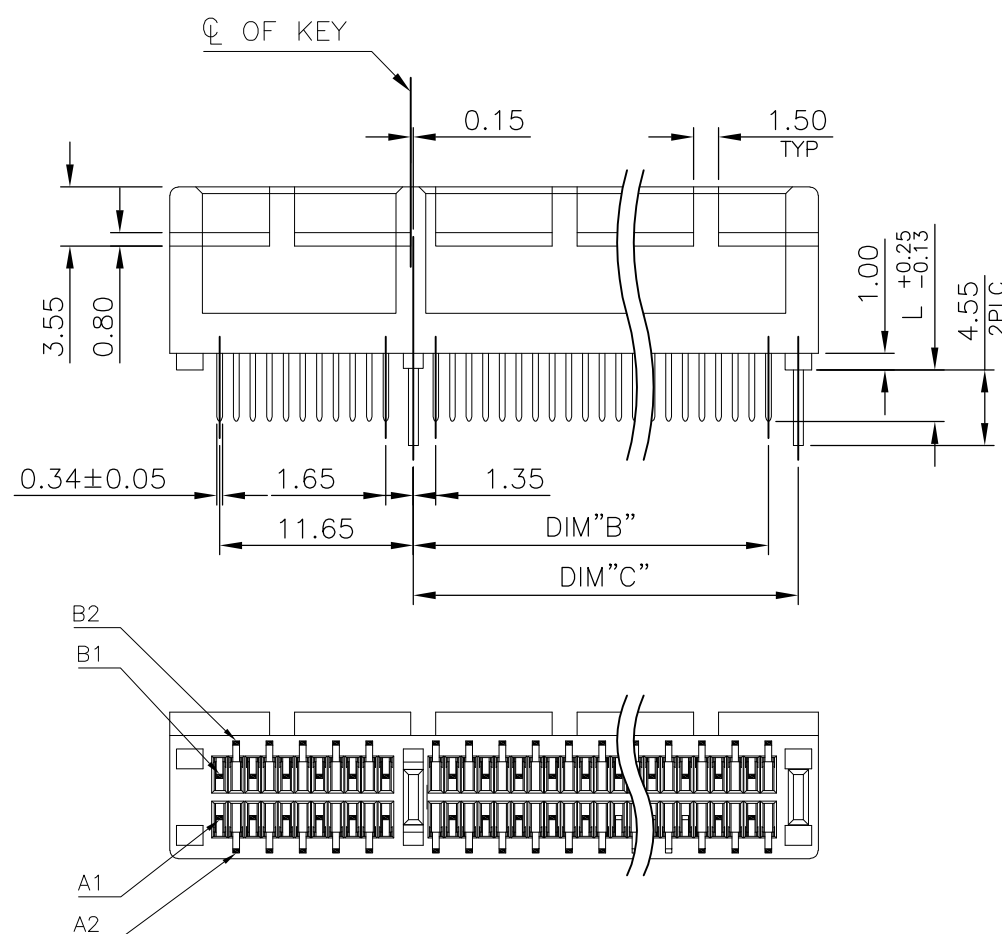
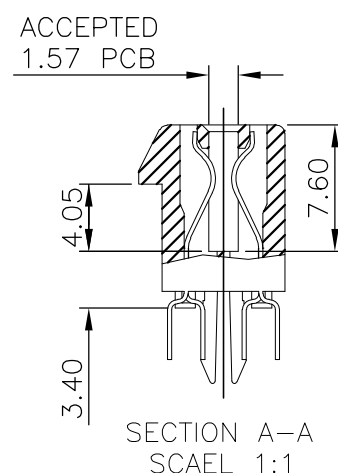
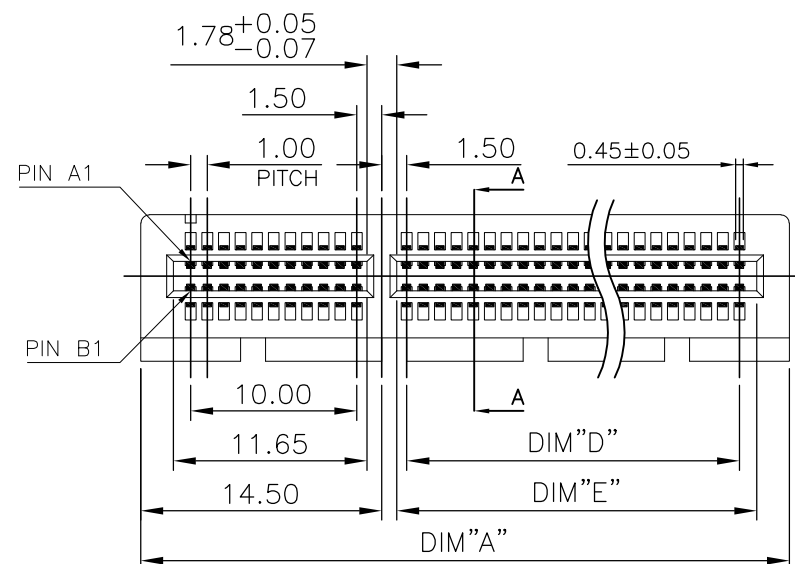
36 POS.: 2.55 GRAMS

64 POS.: 3.90 GRAMS

98 POS.: 5.50 GRAMS

164 POS.: 8.80 GRAMS

5. REFLOW SOLDER CAPABLE TO 260°C PER TE SPEC. TEC-109-201, CONDITION B.



HARD TRAY	NOTE 3 & 5	PA9T	2.30	0.381μm[15μ"] MIN.	71.65	70.0	73.15	71.35	89.0	164	6-	-2
TRAY	NOTE 3	PA46	3.10	0.762μm[30μ"] MIN.	71.65	70.0	73.15	71.35	89.0	164	5-	-2
				0.381μm[15μ"] MIN.							4-	-6
			2.30	GOLD FLASH	71.65	70.0	73.15	71.35	89.0	164	4-	-5
				0.762μm[30μ"] MIN.							4-	-4
			3.10	0.381μm[15μ"] MIN.	71.65	70.0	73.15	71.35	89.0	164	4-	-3
				GOLD FLASH							4-	-2
			2.30	0.762μm[30μ"] MIN.	71.65	70.0	73.15	71.35	89.0	164	4-	-1
				0.381μm[15μ"] MIN.							4-	-6
			3.10	GOLD FLASH	71.65	70.0	73.15	71.35	89.0	164	3-	-5
				0.762μm[30μ"] MIN.							3-	-4
			2.30	0.381μm[15μ"] MIN.	71.65	70.0	73.15	71.35	89.0	164	3-	-3
				GOLD FLASH							3-	-2
			3.10	0.762μm[30μ"] MIN.	71.65	70.0	73.15	71.35	89.0	164	3-	-1
				0.381μm[15μ"] MIN.							3-	-6
			2.30	GOLD FLASH	71.65	70.0	73.15	71.35	89.0	164	2-	-5
				0.762μm[30μ"] MIN.							2-	-4
			3.10	0.381μm[15μ"] MIN.	71.65	70.0	73.15	71.35	89.0	164	2-	-3
				GOLD FLASH							2-	-2
			2.30	0.762μm[30μ"] MIN.	71.65	70.0	73.15	71.35	89.0	164	2-	-1
				0.381μm[15μ"] MIN.							2-	-6
			3.10	GOLD FLASH	71.65	70.0	73.15	71.35	89.0	164	1-	-5
				0.762μm[30μ"] MIN.							1-	-4
			2.30	0.381μm[15μ"] MIN.	71.65	70.0	73.15	71.35	89.0	164	1-	-3
				GOLD FLASH							1-	-2
			3.10	0.762μm[30μ"] MIN.	71.65	70.0	73.15	71.35	89.0	164	1-	-6
				0.381μm[15μ"] MIN.							1-	-5
			2.30	GOLD FLASH	71.65	70.0	73.15	71.35	89.0	164	1-	-4
				0.762μm[30μ"] MIN.							1-	-3
			3.10	0.381μm[15μ"] MIN.	71.65	70.0	73.15	71.35	89.0	164	1-	-2
				GOLD FLASH							1-	-6
PACKAGING	SOLDER CAPACITY	HOUSING MATERIAL	DIM L	GOLD PLATING	DIM E	DIM D	DIM C	DIM B	DIM A	POS.	PART NUMBER	

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DWN B. HSING 21MAY2009

CHK S. CHIEN 21MAY2009

APVD W. KODAMA 21MAY2009

PRODUCT SPEC

108-57375

APPLICATION SPEC

—

WEIGHT 0

CUSTOMER DRAWING



TE Connectivity

PCI EXPRESS CARD EDGE CONNECTOR
VERTICAL, DIP TYPE,(BOARD-LOCK FUNCTION)

SIZE CAGE CODE DRAWING NO RESTRICTED TO

A300779 C-1775801

SCALE 1:1

SHEET 1 OF 4

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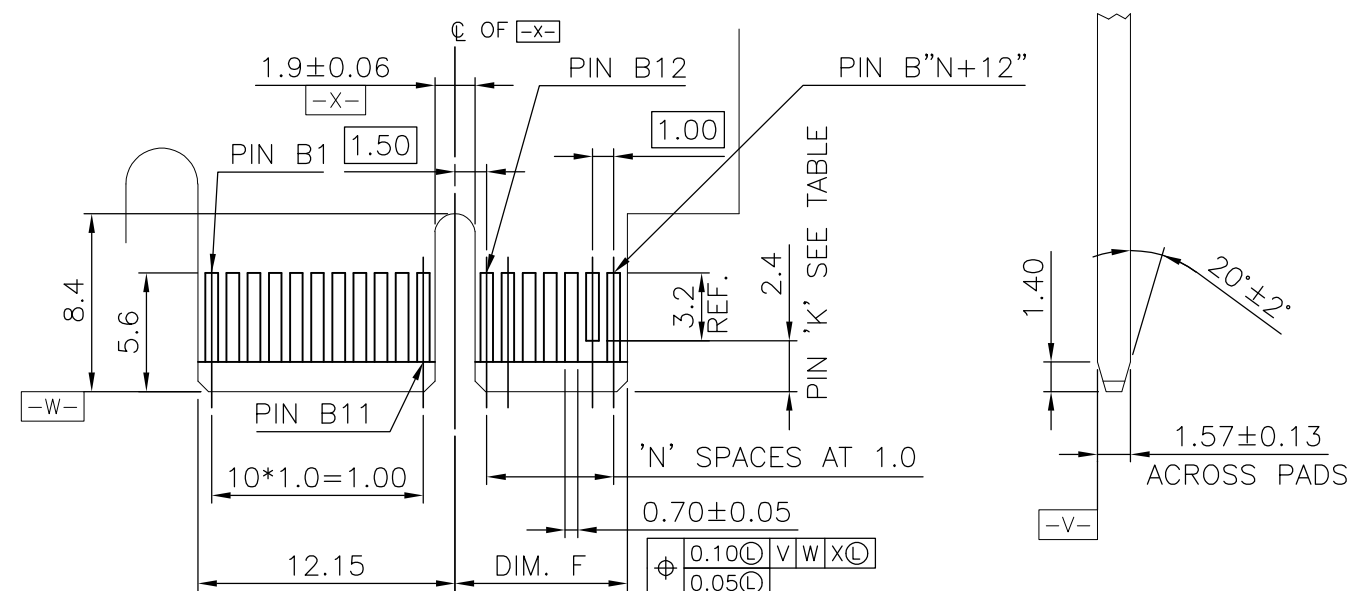
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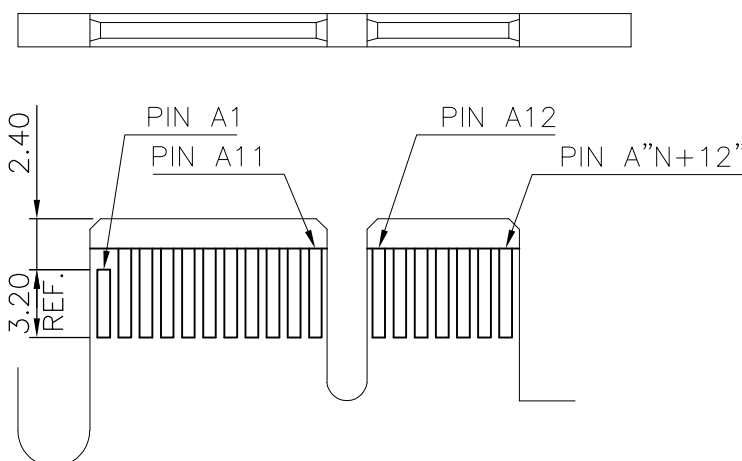
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P	LTR	DESCRIPTION	DATE	DWN	APVD
-	-	SEE SHEET 1	-	-	-

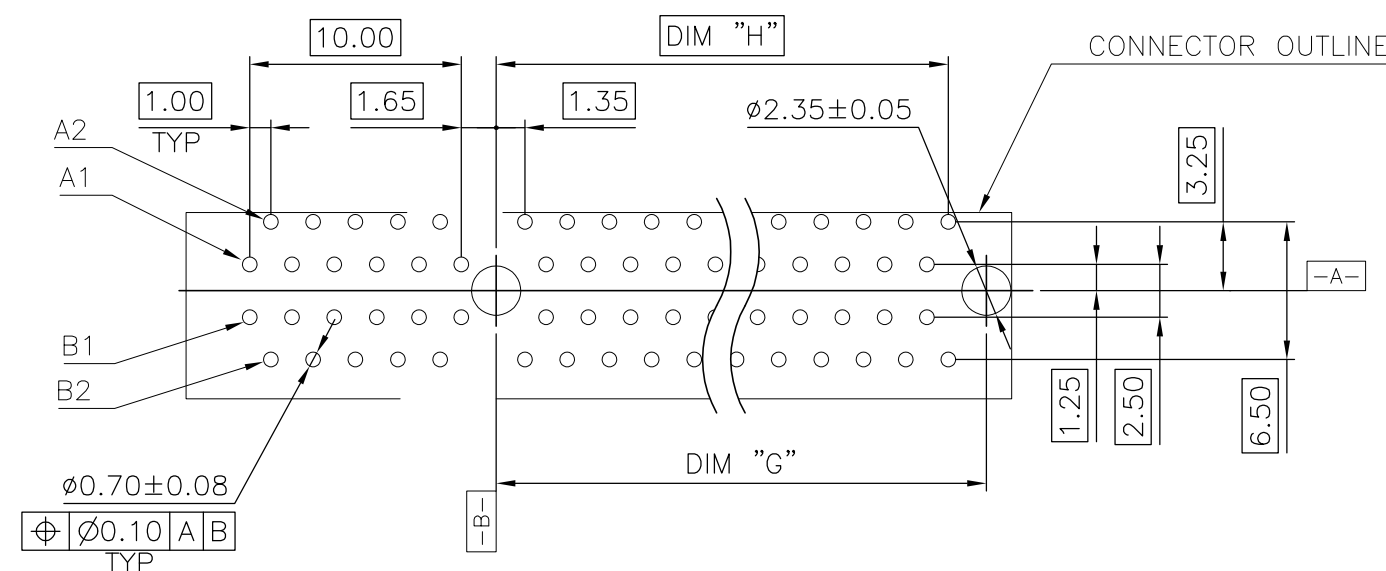
1. NO TIE BAR PERMITTED FROM CARD EDGE TO LEADING EDGE OF PAD FOR PINS A1 AND "K"
2. CHAMFER EDGE MUST BE FREE OF CUTTING BURRS



I/O PANEL DIRECTION
PRIMARY (COMPONENT) SIDE



SECONDARY (SOLDER) SIDE



RECOMMENDED PCB LAYOUT

TOLERANCE: ± 0.05
DIM.L=3.1mm THICKNESS: 2.4mm
DIM.L=2.3mm THICKNESS: 1.6mm

POS.	N	DIM. F	DIM. G	DIM. H	"K"
36	6	8.15	9.15	7.35	B17
64	20	22.15	23.15	21.35	B17,B31
98	37	39.15	40.15	38.35	B17,B31,B48
164	70	72.15	73.15	71.35	B17,B31,B48,B81

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CHK S. CHIEN 21MAY2009

APVD W. KODAMA 21MAY2009

PRODUCT SPEC

APPLICATION SPEC

WEIGHT 0

CUSTOMER DRAWING

STE

TE Connectivity

NAME
PCI EXPRESS CARD EDGE CONNECTOR
VERTICAL, DIP TYPE,(BOARD-LOCK FUNCTION)

SIZE CAGE CODE DRAWING NO RESTRICTED TO

A3 00779 C-1775801

SCALE 1:1 SHEET 2 OF 4 REV D

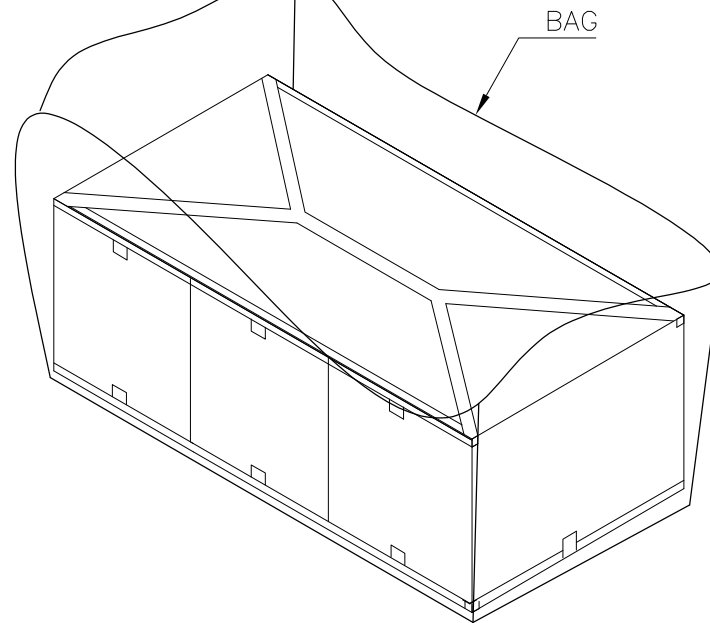
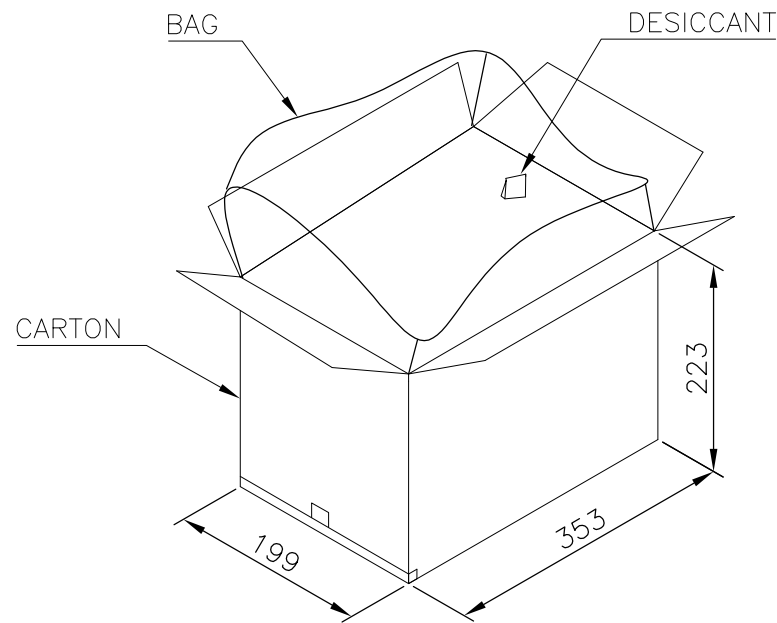
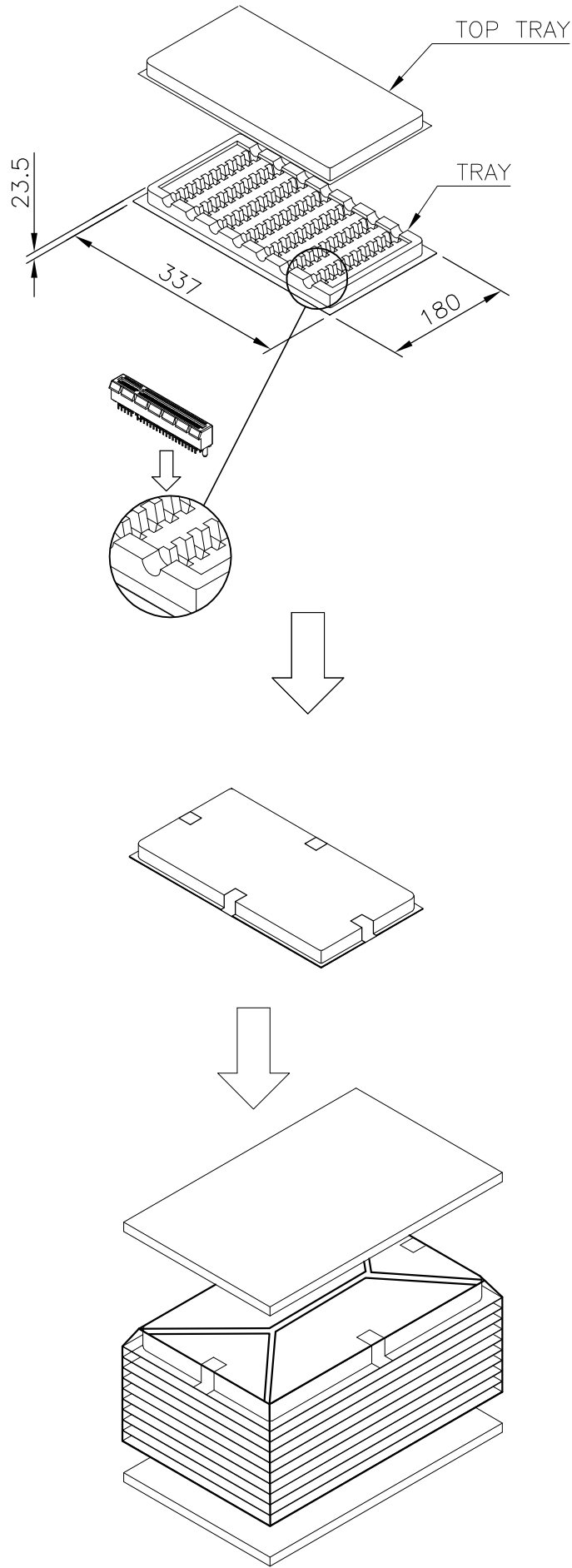
REVISIONS					
P	LTR	DESCRIPTION	DATE	DWN	APVD
	-	SEE SHEET 1	-	-	-

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C

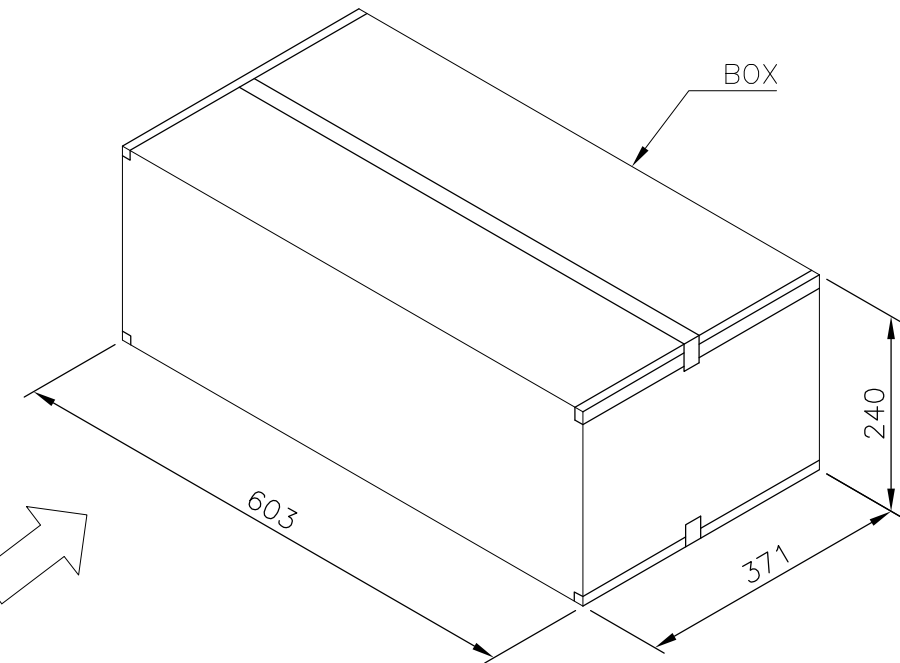
B

A



NOTES :

- MATERIAL :
TRAY : PVC, COLOR: TRANSPARENT.
CARTON: CORRUGATED FIBER
BOX: CORRUGATED FIBER
- DIMENSION :
TRAY: SEE DRAWING
CARTON: SEE DRAWING
BOX : SEE DRAWING
- QUANTITY : SEE TABLE
- WEIGHT : SEE TABLE

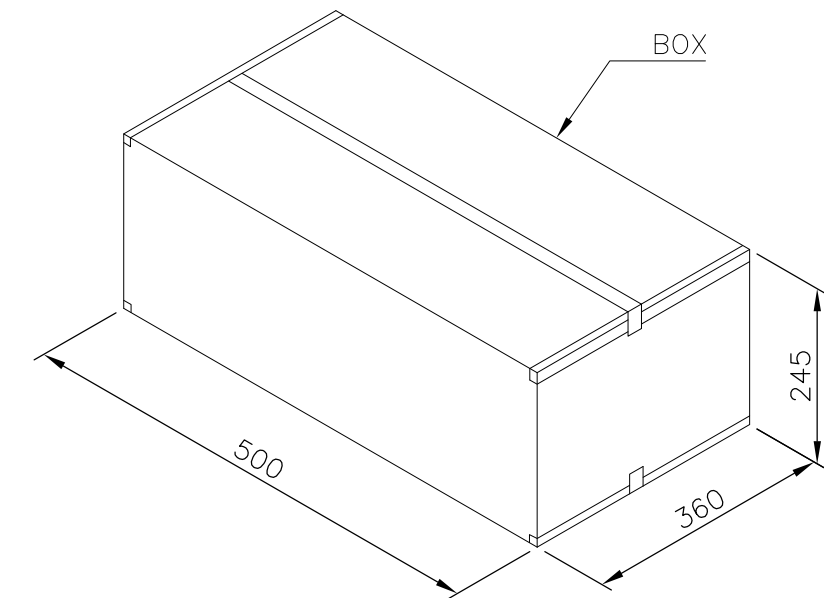


9.6 KG	7.6 KG	30	10	3	900	164
8.5 KG	6.5 KG	40	10	3	1200	98
9.1 KG	7.1 KG	60	10	3	1800	64
7.7 KG	5.7 KG	70	10	3	2100	36
GROSS WEIGHT	NET WEIGHT	PCS/ TRAY	TRAY/ CARTON	CARTON/ BOX	PCS/ BOX	POS

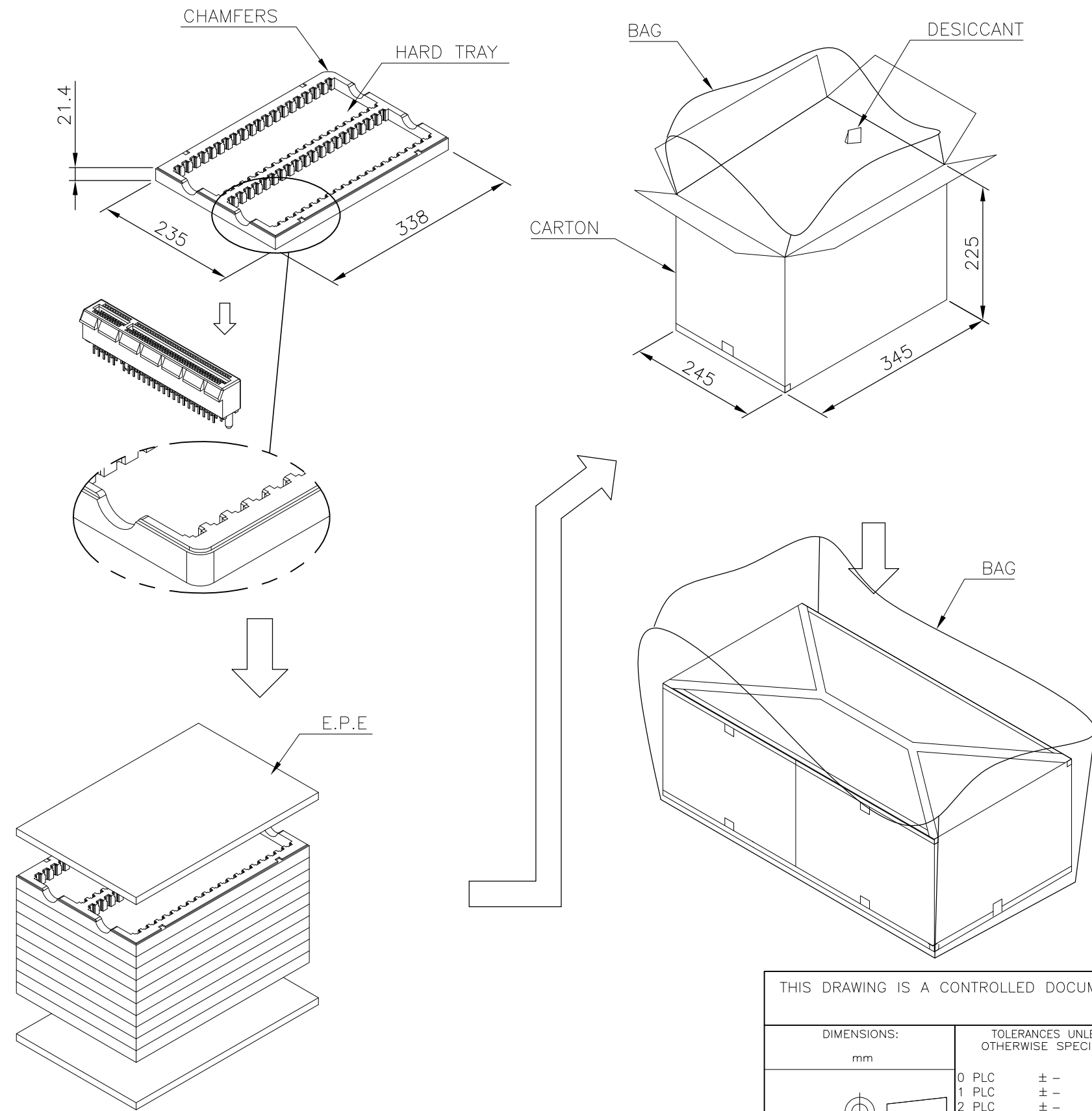
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		CHK S. CHIEN	21MAY2009			
		APVD W. KODAMA	21MAY2009	NAME		
		PRODUCT SPEC		PCI EXPRESS CARD EDGE CONNECTOR VERTICAL, DIP TYPE,(BOARD-LOCK FUNCTION)		
		APPLICATION SPEC		-		
		WEIGHT	0	SIZE	CAGE CODE	DRAWING NO
		CUSTOMER DRAWING		A3	00779	C-1775801
				SCALE	1:1	SHEET
				3 of 4		REV
						D

REVISIONS					
P	LTR	DESCRIPTION	DATE	DWN	APVD
	-	SEE SHEET 1	-	-	-

- NOTES :
- PACKING MATERIAL MET TE SPEC TEC-138-702.
- * CADMIUM AND CADMIUM COMPOUNDS CONTENT:
5 PPM UNDER (PLASTIC, RUBBER, INK, PIGMENT, PAINT)
 - * LEAD, CADMIUM, CHROM VI AND MERCURY IN PACKAGING MATERIALS CONTENT: 100 PPM (COMBINED) UNDER.
1. MATERIAL :
- TRAY: HIPS, COLOR: BLACK.
- CARTON: CORRUGATED FIBER
- BOX: CORRUGATED FIBER
- TRANSPARENT BAG: PE, SIZE: 500mm*380mm*0.06mm
640mm*510mm*0.06mm
2. EACH BAG SHALL BE INCLUDED:
- * DESICCANT



11.5 Kg	7.0 Kg	40	10	2	800	164
GROSS WEIGHT	NET WEIGHT	PCS/ TRAY	TRAY/ CARTON	CARTON/ BOX	PCS/ BOX	POS



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		APPLICATION SPEC				
		WEIGHT	0	SIZE	CAGE CODE	DRAWING NO
		CUSTOMER DRAWING		A300779		C-1775801
				SCALE	SHEET	REV
				1:1	4 of 4	D



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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